

LOCATION DETAIL

NOTES:

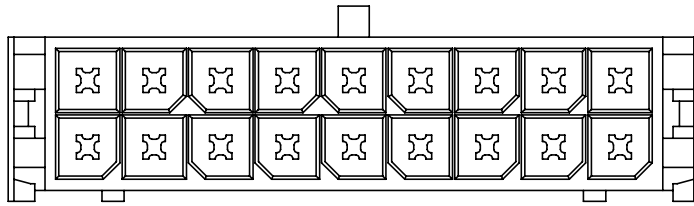
- MATERIAL:
  - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
  - CONTACT: COPPER ALLOY
  - FITTING NAIL: COPPER ALLOY
- FINISH:
  - CONTACT:
    - 50u" MIN NICKEL UNDERPLATING OVERALL.
    - N: 60u" MIN MATTE TIN OVERALL..
    - D: 30u" MIN Au ON CONTACT AREA
    - 60u" MIN MATTE TIN ON SOLDER AREA
    - 1: GOLD FLASH ON CONTACT AREA
    - 60u" MIN MATTE TIN ON SOLDER AREA
- REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- SPEC. PLS. REFER TO PS-57959-XXXXX-XXX
- PACKAGE PLS. REFER TO 59193-XXXXX-05-TRP
- PART NUMBER

59193-XXX X X-XXX

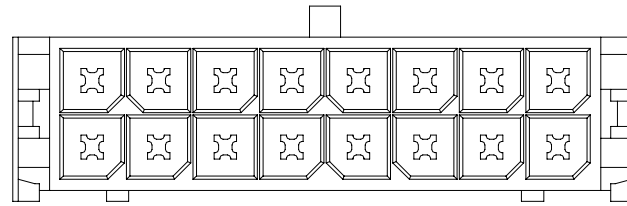
NO OF CKT: 002:FOR SMD TYPE  
 PACKING: PLATING  
 0:TAPE&REEL N: MATTE TIN  
 D: 30u" MIN Au  
 1: GOLD FLASH

CKT	DIM A	DIM B	DIM C	DIM D
2	6.65	NA	4.30	6.74
4	9.65	3.00	7.30	
6	12.65	6.00	10.30	
8	15.65	9.00	13.30	1.60
10	18.65	12.00	16.30	
12	21.65	15.00	19.30	
14	24.65	18.00	22.30	
16	27.65	21.00	25.30	
18	30.65	24.00	28.30	
20	33.65	27.00	31.30	
22	36.65	30.00	34.30	
24	39.65	33.00	37.30	

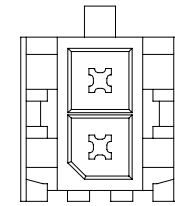
<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ <b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X: ±0.5 XX: ±0.38 .XXX: ±0.25 XXX: ±0.15 ANGLES: ±2°	DRAWN BY: Zhu,SiBiao DATE: 23/11/13	
	CHECKED BY: Lu,Jing Quan DATE: 23/11/13	
	APPROVED BY: hsieh,tu yu DATE: 23/11/13	UNITS: mm SCALE: 3:1
	SIZE: A4 REV: B	RFG NO.: N/A DWG NO.: 59193-XXXXX-XXX
	SHEET NO.: 2 OF 3	



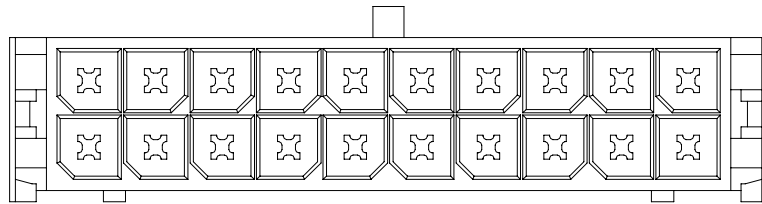
18-CKT



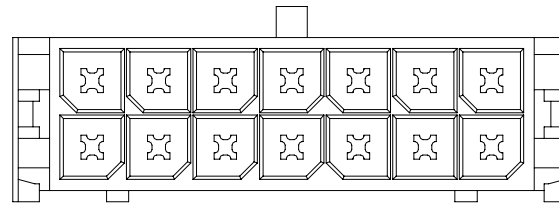
16-CKT



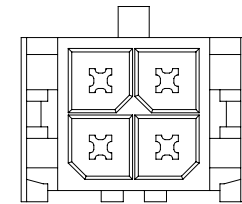
2-CKT



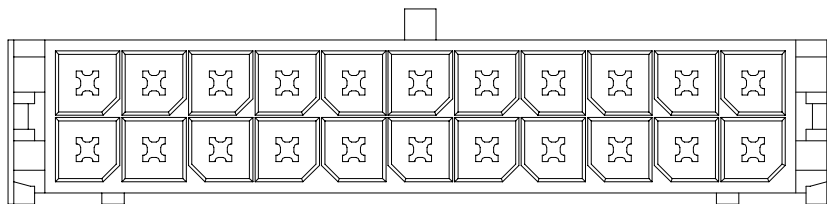
20-CKT



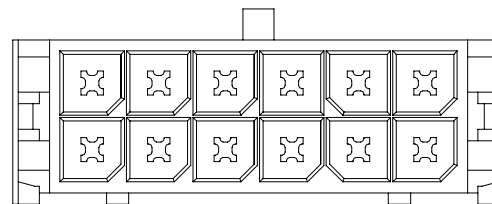
14-CKT



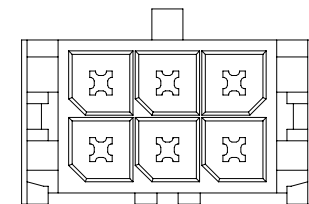
4-CKT



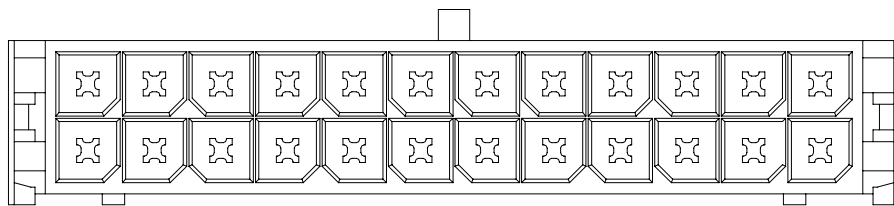
22-CKT



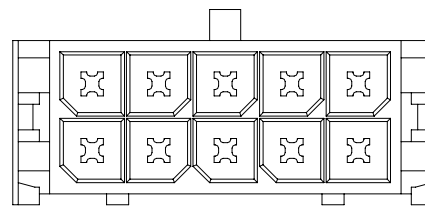
12-CKT



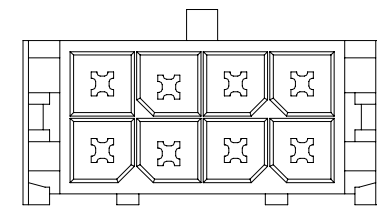
6-CKT



24-CKT



10-CKT



8-CKT

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	UNITS mm		SIZE A4
	SCALE 3 : 1	SHEET NO. 3 OF 3	REV B
			DWG NO. 59193-XXXX-XXX